

# STPS1L20MF

## Low drop power Schottky rectifier in flat package

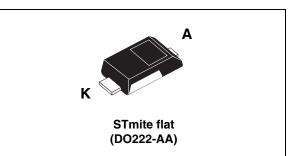
## Features

- Very low profile package: 0.85 mm
- Backward compatible with standard STmite footprint
- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop for higher efficiency and extended battery life
- Low thermal resistance
- Avalanche capability specified

## Description

Single Schottky rectifier suited for switch mode power supplies and high frequency dc to dc converters.

Packaged in STmite flat, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications. Due to the very small size of the package this device fits battery powered equipment (cellular, notebook, PDA's, printers) as well as chargers and PCMCIA cards.



#### Table 1. Device summary

Symbol	Value
I <sub>F(AV)</sub>	1 A
V <sub>RRM</sub>	20 V
T <sub>j</sub> (max)	150 °C
V <sub>F</sub> (max)	0.37 V

1/7

#### **Characteristics** 1

#### Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage	20	V	
I <sub>F(RMS)</sub>	Forward current rms	2	А	
I <sub>F(AV)</sub>	Average forward current $T_c = 140 \ ^\circ C \ \delta = 0.5$		1	А
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		50	А
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p = 1 \ \mu s \ T_j = 25 \ ^{\circ}C$		1400	W
T <sub>stg</sub>	Storage temperature range	- 65 to + 150	°C	
Тj	Maximum operating junction temperature <sup>(1)</sup>	150	°C	
dV/dt	Critical rate of rise of reverse voltage (rated	10000	V/µs	

1.  $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

#### Table 3. **Thermal resistance**

Symbol	Parameter	Value	Unit
R <sub>th(j-c)</sub>	Junction to case	20	°C/W
$R_{th(j-a)}^{(1)}$	Junction to ambient	250	°C/W

1. Mounted with minimum recommended pad size, PC board FR4

#### Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup> Reve		T <sub>j</sub> = 25 °C			0.015	0.075	
		T <sub>j</sub> = 85 °C	$V_{R} = V_{RRM}$		0.90	4.50	
	Povoroo lookogo ourront	T <sub>j</sub> = 25 °C	V = 10 V		0.005	0.035	mA
	Reverse leakage current	T <sub>j</sub> = 85 °C	V <sub>R</sub> = 10 V		0.45	2.50	
		T <sub>j</sub> = 25 °C			0.003	0.025	
		T <sub>j</sub> = 85 °C	V <sub>R</sub> = 5 V		0.30	1.60	
V <sub>F</sub> <sup>(1)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 1 A		0.38	0.43	
		T <sub>j</sub> = 85 °C			0.32	0.37	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 2 A		0.42	0.47	
		T <sub>j</sub> = 85 °C			0.37	0.42	V
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 3 A		0.46	0.53	v
		T <sub>j</sub> = 85 °C			0.42 0.49		
		T <sub>j</sub> = 25 °C T <sub>j</sub> = 85 °C	I <sub>F</sub> = 4 A		0.50	0.60	
		T <sub>j</sub> = 85 °C			0.46	0.56	

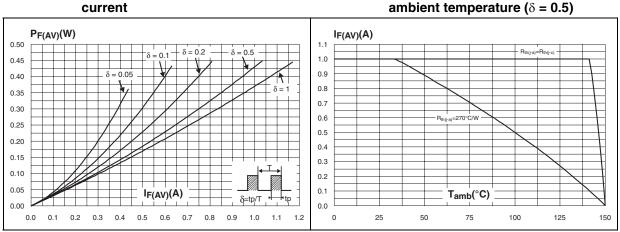
1. Pulse test: = 380  $\mu$ s,  $\delta$  < 2%

To evaluate the conduction losses use the following equation: P = 0.32 x  $I_{F(AV)}$  + 0.05  ${I_F}^2_{(RMS)}$ 



Figure 3.

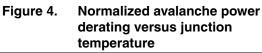
Average forward current versus



# Figure 1. Conduction losses versus average Figure 2. current

Normalized avalanche power

derating versus pulse duration



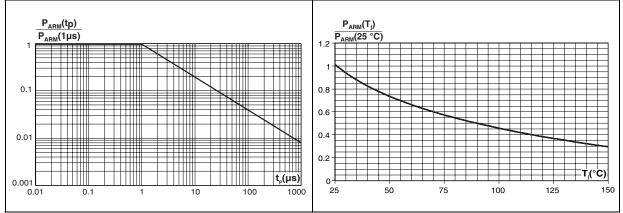
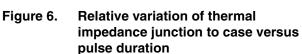
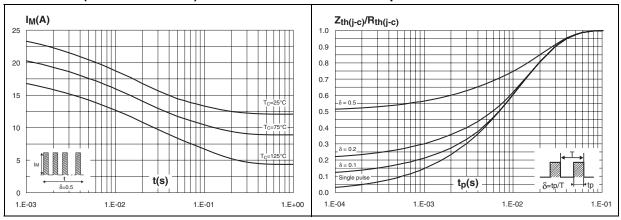


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)





### Doc ID 12640 Rev 2

**Reverse leakage currrent versus** 

junction temperature

# Figure 7. Reverse leakage currrent versus reverse voltage applied (typical values)

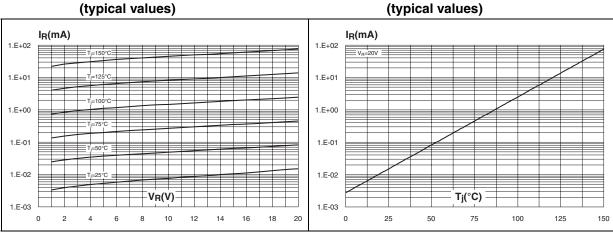
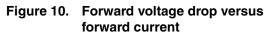


Figure 8.

# Figure 9. Junction capacitance versus reverse voltage applied (typical values)



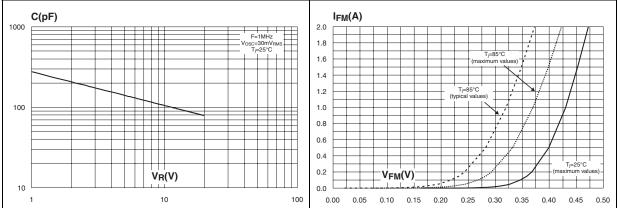
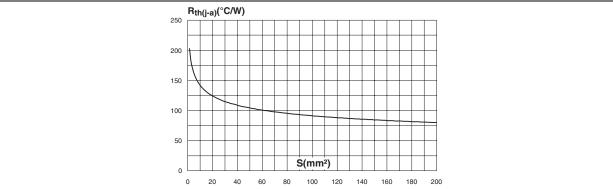


Figure 11. Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, copper thickness =  $35 \mu m$ , typical values)





## 2 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.

Table 5. STmite flat dimensions

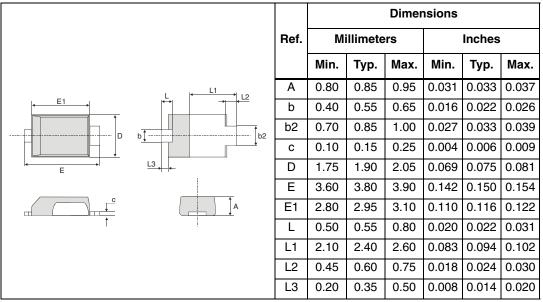
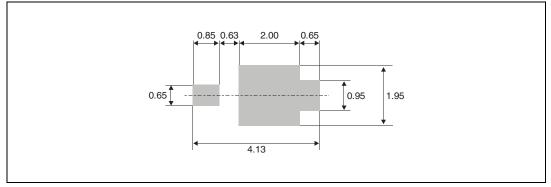


Figure 12. STmite flat recommended footprint (all dimensions in mm)





## **3** Ordering information

## Table 6.Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1L20MF	F1L2	STmite flat	16 mg	12000	Tape and reel

## 4 Revision history

### Table 7.Document revision history

Date	Revision	Changes
21-Aug-2006	1	First issue.
07-Jul-2011	2	Reformatted to current standards. Updated caption for Figure 6.



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